

Material Content Datasheet



Performance Motion Devices

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MC50000IOABN.G*			
Packaging Data		Package Size	14mm x 14mm
		Package Type	100-pin TQFP
		Plating / Layer Composition	100% Annealed Tin (Sn)**
		Total Weight (mg)	573
Hazmat Data	RoHS	Lead (ppm)	ND***
		Mercury (ppm)	ND
		Cadmium (ppm)	ND
		Hexavalent-Chromium (ppm)	ND
		PBB (ppm)	ND
		PBDE (ppm)	ND
	Green	Bromine (ppm)	ND
		Antimony (ppm)	ND
Process Data		MSL	3
		Max Solder Peak Temp (Reflow) C°	260
		Max Solder Peak Duration (Reflow) Seconds	30
		Max Solder Peak Temp (Wave) C°	Not Applicable
		Max Solder Peak Duration (Wave) Seconds	Not Applicable
		Confirm IPC/JEDEC J-STD-020C (without any limitations) (JULY 2004)	Yes
		Non Magnetic Component	Yes
EOL Status		Recommended for new designs. No EOL planned.	
Document Rev		1.1 2/8/2006	

* R = RoHS compliant, G = Green compliant (RoHS and Sb/Br-free)
 x (lower case) = any number from 0-9
 X (upper case) = any letter from A-Z

** Minimum 1 hour annealing bake @ 150°C within 24 hours of Sn Matte plating process to eliminate whiskering

*** ND = Non-Detectable